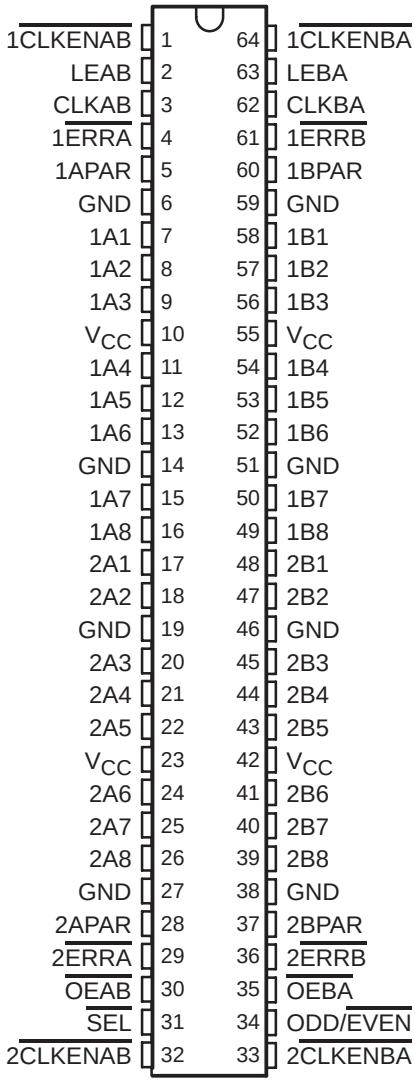
- **Member of the Texas Instruments Widebus™ Family**
- **UBT ™ Transceiver Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode**
- **Operates From 1.65 V to 3.6 V**
- **Max t_{pd} of 4.4 ns at 3.3 V**
- **±24-mA Output Drive at 3.3 V**
- **Simultaneously Generates and Checks Parity**
- **Option to Select Generate Parity and Check or Feed-Through Data/Parity in A-to-B or B-to-A Directions**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**

DGG PACKAGE
(TOP VIEW)



description/ordering information

This 18-bit (dual-octal) noninverting registered transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH16901 is a dual 9-bit to dual 9-bit parity transceiver with registers. The device can operate as a feed-through transceiver or it can generate/check parity from the two 8-bit data buses in either direction.

The SN74ALVCH16901 features independent clock (CLKAB or CLKBA), latch-enable (LEAB or LEBA), and dual 9-bit clock-enable ($\overline{\text{CLKENAB}}$ or $\overline{\text{CLKENBA}}$) inputs. It also provides parity-enable ($\overline{\text{SEL}}$) and parity-select (ODD/$\overline{\text{EVEN}}$) inputs and separate error-signal ($\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$) outputs for checking parity. The direction of data flow is controlled by $\overline{\text{OEAB}}$ and $\overline{\text{OEBA}}$. When $\overline{\text{SEL}}$ is low, the parity functions are enabled. When $\overline{\text{SEL}}$ is high, the parity functions are disabled, and the device acts as an 18-bit registered transceiver.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	TSSOP − DGG	Tape and reel	SN74ALVCH16901DGGR	ALVCH16901

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus and UBT are trademarks of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 2004, Texas Instruments Incorporated

description/ordering information (continued)

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The A and B I/Os and APAR and BPAR inputs have bus-hold circuitry. Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

Function Tables

FUNCTION†

INPUTS					OUTPUT
$\overline{CLKENAB}$	$\overline{OEAB}$	LEAB	CLKAB	A	B
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B_0‡
L	L	L	↑	L	L
L	L	L	↑	H	H
L	L	L	L	X	B_0‡
L	L	L	H	X	B_0§

† A-to-B data flow is shown; B-to-A flow is similar, but uses $\overline{OEBA}$, LEBA, and $\overline{CLKENBA}$.
‡ Output level before the indicated steady-state input conditions were established
§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

PARITY ENABLE

INPUTS			OPERATION OR FUNCTION	
$\overline{SEL}$	$\overline{OEBA}$	$\overline{OEAB}$		
L	H	L	Parity is checked on port A and is generated on port B.	
L	L	H	Parity is checked on port B and is generated on port A.	
L	H	H	Parity is checked on port B and port A.	
L	L	L	Parity is generated on port A and B if device is in FF mode.	
H	L	L	Parity functions are disabled; device acts as a standard 18-bit registered transceiver.	Q_A data to B, Q_B data to A
H	L	H		Q_B data to A
H	H	L		Q_A data to B
H	H	H		Isolation

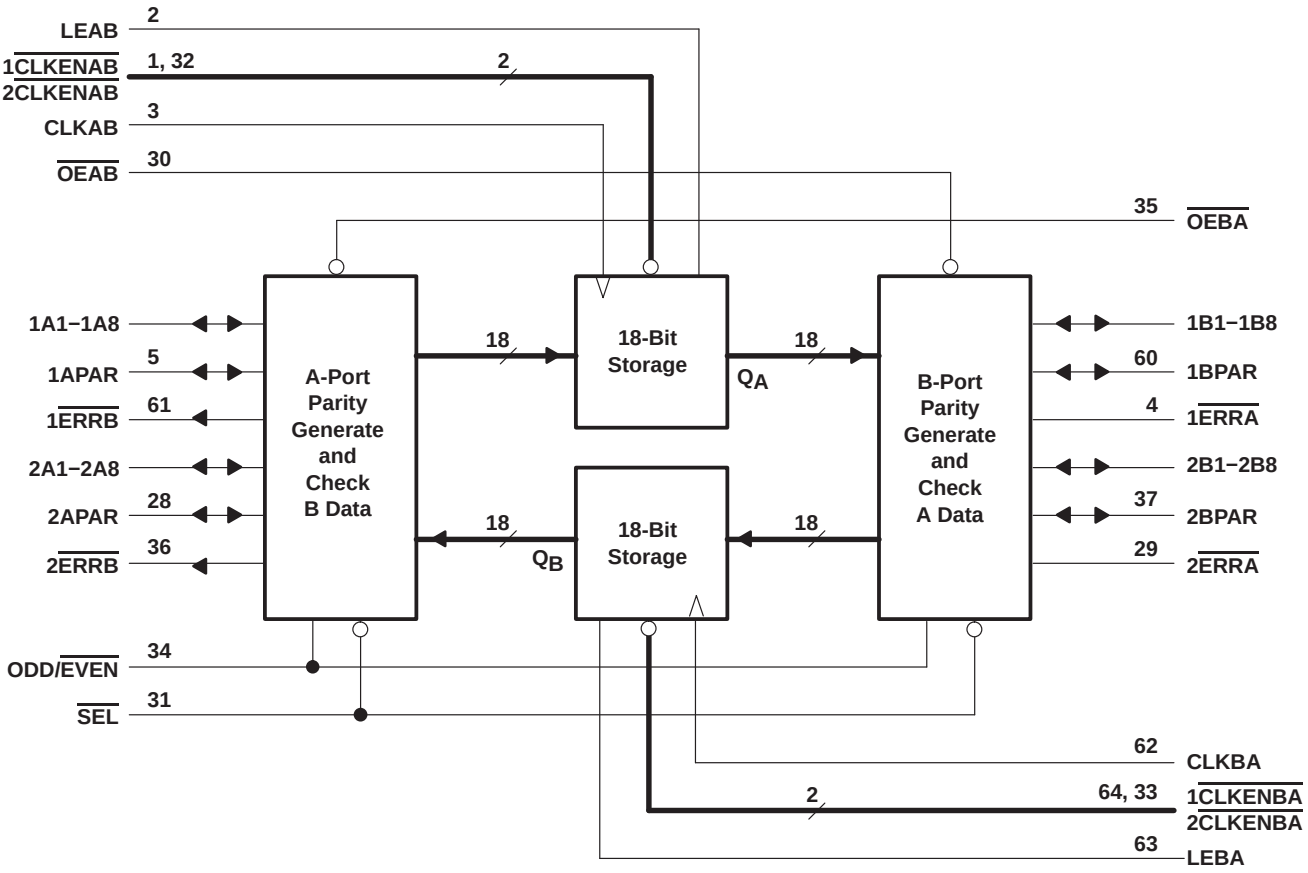
Function Tables (Continued)

PARITY

INPUTS								OUTPUTS			
$\overline{SEL}$	$\overline{OEBA}$	$\overline{OEAB}$	ODD/$\overline{EVEN}$	Σ OF INPUTS A1−A8 = H	Σ OF INPUTS B1−B8 = H	APAR	BPAR	APAR	$\overline{ERRA}$	BPAR	$\overline{ERRB}$
L	H	L	L	0, 2, 4, 6, 8	N/A	L	N/A	N/A	H	L	Z
L	H	L	L	1, 3, 5, 7	N/A	L	N/A	N/A	L	H	Z
L	H	L	L	0, 2, 4, 6, 8	N/A	H	N/A	N/A	L	L	Z
L	H	L	L	1, 3, 5, 7	N/A	H	N/A	N/A	H	H	Z
L	L	H	L	N/A	0, 2, 4, 6, 8	N/A	L	L	Z	N/A	H
L	L	H	L	N/A	1, 3, 5, 7	N/A	L	H	Z	N/A	L
L	L	H	L	N/A	0, 2, 4, 6, 8	N/A	H	L	Z	N/A	L
L	L	H	L	N/A	1, 3, 5, 7	N/A	H	H	Z	N/A	H
L	H	L	H	0, 2, 4, 6, 8	N/A	L	N/A	N/A	L	H	Z
L	H	L	H	1, 3, 5, 7	N/A	L	N/A	N/A	H	L	Z
L	H	L	H	0, 2, 4, 6, 8	N/A	H	N/A	N/A	H	H	Z
L	H	L	H	1, 3, 5, 7	N/A	H	N/A	N/A	L	L	Z
L	L	H	H	N/A	0, 2, 4, 6, 8	N/A	L	H	Z	N/A	L
L	L	H	H	N/A	1, 3, 5, 7	N/A	L	L	Z	N/A	H
L	L	H	H	N/A	0, 2, 4, 6, 8	N/A	H	H	Z	N/A	H
L	L	H	H	N/A	1, 3, 5, 7	N/A	H	L	Z	N/A	L
L	H	H	L	0, 2, 4, 6, 8	0, 2, 4, 6, 8	L	L	Z	H	Z	H
L	H	H	L	1, 3, 5, 7	1, 3, 5, 7	L	L	Z	L	Z	L
L	H	H	L	0, 2, 4, 6, 8	0, 2, 4, 6, 8	H	H	Z	L	Z	L
L	H	H	L	1, 3, 5, 7	1, 3, 5, 7	H	H	Z	H	Z	H
L	H	H	H	0, 2, 4, 6, 8	0, 2, 4, 6, 8	L	L	Z	L	Z	L
L	H	H	H	1, 3, 5, 7	1, 3, 5, 7	L	L	Z	H	Z	H
L	H	H	H	0, 2, 4, 6, 8	0, 2, 4, 6, 8	H	H	Z	H	Z	H
L	H	H	H	1, 3, 5, 7	1, 3, 5, 7	H	H	Z	L	Z	L
L	L	L	L	N/A	N/A	N/A	N/A	PE†	Z	PE†	Z
L	L	L	H	N/A	N/A	N/A	N/A	PO‡	Z	PO‡	Z

† Parity output is set to the level so that the specific bus side is set to even parity.
‡ Parity output is set to the level so that the specific bus side is set to odd parity.

functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 4.6 V
Input voltage range, V_I: Except I/O ports (see Note 1) . . . . . −0.5 V to 4.6 V
I/O ports (see Notes 1 and 2 . . . . . −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Notes 1 and 2) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) . . . . . −50 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . −50 mA
Continuous output current, I_O . . . . . ±50 mA
Continuous current through each V_{CC} or GND . . . . . ±100 mA
Package thermal impedance, θ_{JA} (see Note 3) . . . . . 55°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed..
2. This value is limited to 4.6 V maximum.
3. The package thermal impedance is calculated in accordance with JESD 51−7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		1.65	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		V
		V_{CC} = 2.3 V to 2.7 V	1.7		
		V_{CC} = 2.7 V to 3.6 V	2		
V_{IL}	Low-level input voltage	V_{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	V
		V_{CC} = 2.3 V to 2.7 V		0.7	
		V_{CC} = 2.7 V to 3.6 V		0.8	
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 1.65 V		−4	mA
		V_{CC} = 2.3 V		−12	
		V_{CC} = 2.7 V		−12	
		V_{CC} = 3 V		−24	
I_{OL}	Low-level output current	V_{CC} = 1.65 V		4	mA
		V_{CC} = 2.3 V		12	
		V_{CC} = 2.7 V		12	
		V_{CC} = 3 V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T_A	Operating free-air temperature		−40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP†	MAX	UNIT
V_{OH}		I_{OH} = −100 µA	1.65 V to 3.6 V	V_{CC} − 0.2			V
		I_{OH} = −4 mA	1.65 V	1.2			
		I_{OH} = −6 mA	2.3 V	2			
		I_{OH} = −12 mA	2.3 V	1.7			
			2.7 V	2.2			
			3 V	2.4			
		I_{OH} = −24 mA	3 V	2			
V_{OL}		I_{OL} = 100 µA	1.65 V to 3.6 V			0.2	V
		I_{OL} = 4 mA	1.65 V			0.45	
		I_{OL} = 6 mA	2.3 V			0.4	
		I_{OL} = 12 mA	2.3 V			0.7	
			2.7 V			0.4	
		I_{OL} = 24 mA	3 V			0.55	
I_I		$V_I = V_{CC}$ or GND	3.6 V			±5	µA
$I_{I(hold)}$		V_I = 0.58 V	1.65 V	25			µA
		V_I = 1.07 V	1.65 V	−25			
		V_I = 0.7 V	2.3 V	45			
		V_I = 1.7 V	2.3 V	−45			
		V_I = 0.8 V	3 V	75			
		V_I = 2 V	3 V	−75			
		V_I = 0 to 3.6 V‡	3.6 V			±500	
I_{OZ}§		$V_O = V_{CC}$ or GND	3.6 V			±10	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	3.6 V			40	µA
ΔI_{CC}		One input at V_{CC} − 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V			750	µA
C_i	Control inputs	$V_I = V_{CC}$ or GND	3.3 V		3		pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	3.3 V		7.5		pF
C_o	$\overline{ERR}$ ports	$V_O = V_{CC}$ or GND	3.3 V		6		pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.
§ For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V_{CC} = 1.8 V		V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			†		125		125		125	MHz
t_w	Pulse duration	CLK↑	†		3		3		3		ns
		LE high	†		3		3		3		
t_{su}	Setup time	A, APAR or B, BPAR before CLK↑	†		1.9		2		1.7		ns
		$\overline{\text{CLKEN}}$ before CLK↑	†		2.1		2.1		1.7		
		A, APAR or B, BPAR before LE↓	†		1.4		1.3		1.2		
t_h	Hold time	A, APAR or B, BPAR after CLK↑	†		0.4		0.4		0.5		ns
		$\overline{\text{CLKEN}}$ after CLK↑	†		0.5		0.5		0.7		
		A, APAR or B, BPAR after LE↓	†		0.9		1.1		0.9		

† This information was not available at the time of publication.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 1.8 V		V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			†		125		125		125		MHz
t_{pd}	A or B	B or A		†	1	5.2		4.8	1	4.4	ns
		BPAR or APAR		†	2	8.9		7.6	2	6.7	
	APAR or BPAR	BPAR or APAR		†	1	5.7		5.2	1	4.7	
		$\overline{ERRA}$ or $\overline{ERRB}$		†	2	9.7		8.7	2	7.5	
	ODD/$\overline{EVEN}$	$\overline{ERRA}$ or $\overline{ERRB}$		†	1.5	8.7		7.9	1.5	6.8	
		BPAR or APAR		†	1.5	8.3		7.6	1.5	6.5	
	$\overline{SEL}$	BPAR or APAR		†	1	6.1		5.9	1	5.1	
	CLKAB or CLKBA	A or B		†	1	6.4		5.8	1	5.1	
		BPAR or APAR parity feed through		†	1.5	7.1		6.3	1.5	5.6	
		BPAR or APAR parity generated		†	2.5	10.2		8.7	2	7.7	
		$\overline{ERRA}$ or $\overline{ERRB}$		†	2.5	10.5		8.9	2	7.9	
	LEAB or LEBA	A or B		†	1	6		5.5	1	4.8	
		BPAR or APAR parity feed through		†	1.5	6.7		6	1.5	5.3	
		BPAR or APAR parity generated		†	2.5	9.8		8.3	2	7.4	
		$\overline{ERRA}$ or $\overline{ERRB}$		†	2.5	9.9		8.5	2	7.5	
t_{en}	$\overline{OEAB}$ or $\overline{OEBA}$	B, BPAR or A, APAR		†	1.4	6.3		6.1	1	5.3	ns
t_{dis}	$\overline{OEAB}$ or $\overline{OEBA}$	B, BPAR or A, APAR		†	1.3	6.1		5.2	1.5	4.9	ns
t_{en}	$\overline{OEAB}$ or $\overline{OEBA}$	$\overline{ERRA}$ or $\overline{ERRB}$		†	1.4	6.2		5.5	1	4.9	ns
t_{dis}	$\overline{OEAB}$ or $\overline{OEBA}$	$\overline{ERRA}$ or $\overline{ERRB}$		†	1.3	7.3		6.5	1	5.7	ns
t_{en}	$\overline{SEL}$	$\overline{ERRA}$ or $\overline{ERRB}$		†	1.4	6.7		6.5	1	5.5	ns
t_{dis}	$\overline{SEL}$	$\overline{ERRA}$ or $\overline{ERRB}$		†	1.3	6.4		5.4	1.5	4.9	ns

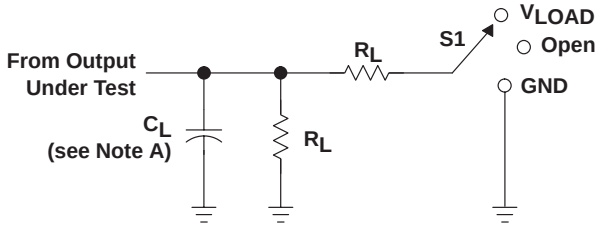
† This information was not available at the time of publication.

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC} = 1.8 V	V_{CC} = 2.5 V	V_{CC} = 3.3 V	UNIT
			TYP	TYP	TYP	
C_{pd} Power dissipation capacitance	Outputs enabled	C_L = 50 pF, f = 10 MHz	†	22	27	pF
	Outputs disabled		†	5	8	

† This information was not available at the time of publication.

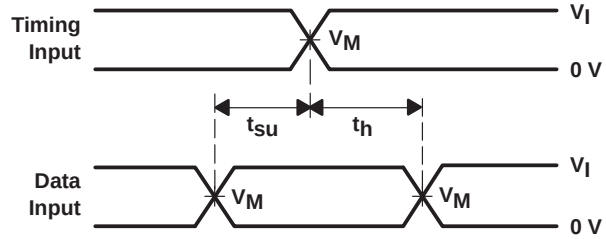
PARAMETER MEASUREMENT INFORMATION



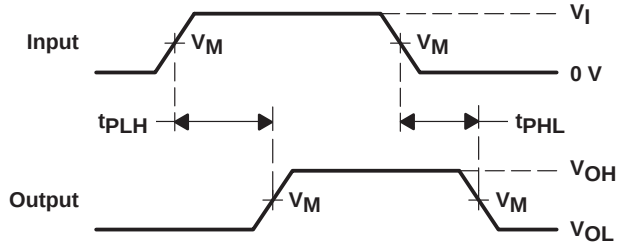
LOAD CIRCUIT

TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open V_{LOAD} GND

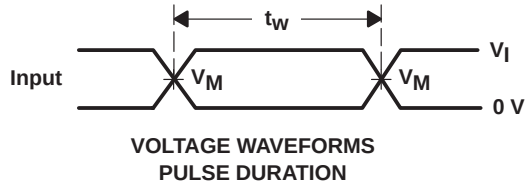
V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
1.8 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 kΩ	0.15 V
2.5 V ± 0.2 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3 V ± 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



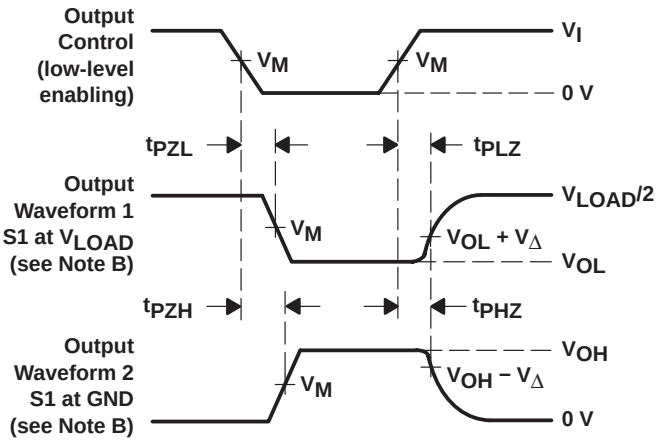
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALVCH16901DGGR	ACTIVE	TSSOP	DGG	64	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16901	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

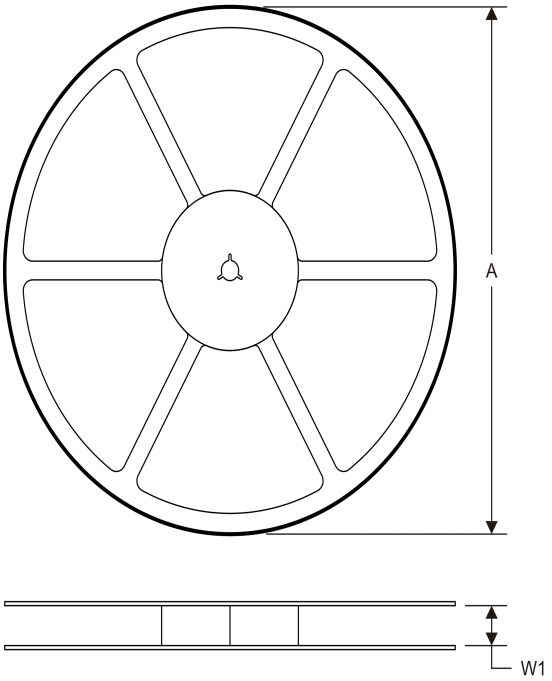
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

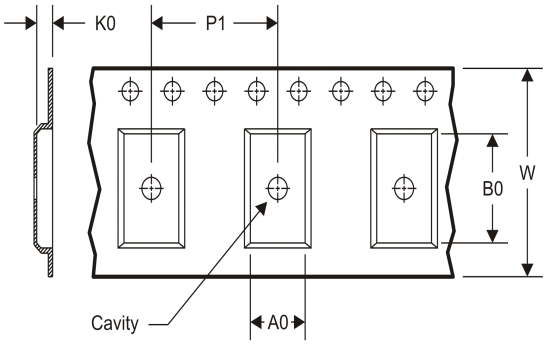
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



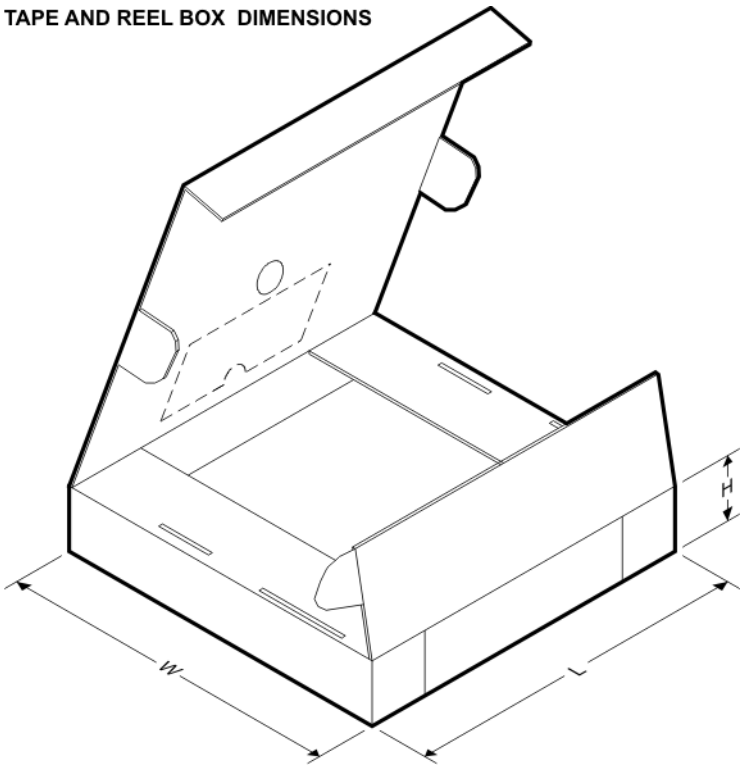
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16901DGGR	TSSOP	DGG	64	2000	330.0	24.4	8.4	17.3	1.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

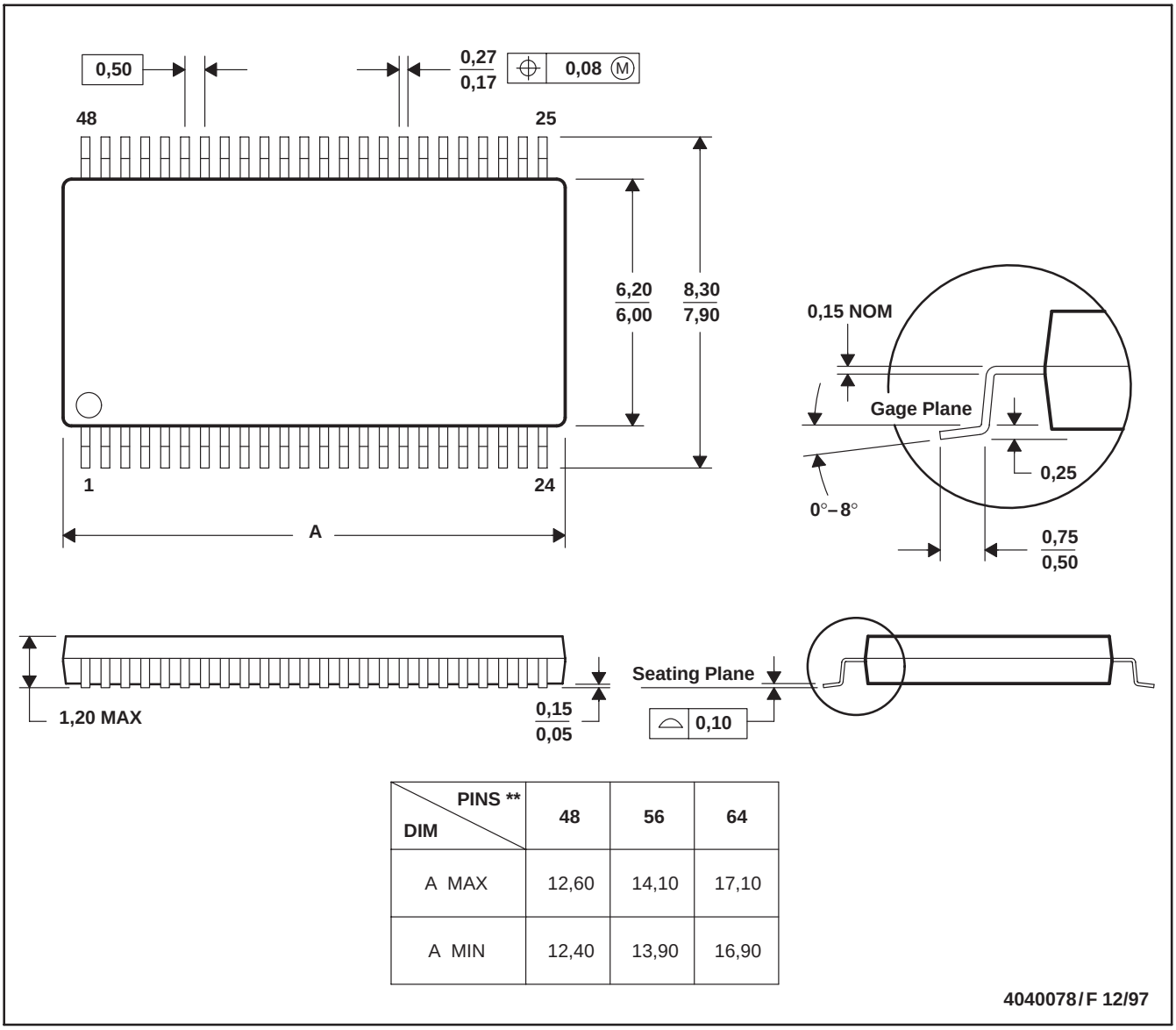


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16901DGGR	TSSOP	DGG	64	2000	367.0	367.0	45.0

DGG (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN



DIM \ PINS **	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (https:www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2021, Texas Instruments Incorporated